

IN THE SPECIFICATION

Please amend the specification as follows, with a marked-up copy of the amendment being included in an Appendix attached to this reply.

**Please amend the first full paragraph of page 14 as follows:**

D<sup>1</sup> Particularly, the alignment marks 18, 19 are preferably formed in the opening portions exposing only the surface of the conductor layer from the solder resist layer formed on the conductor layer (including the viahole). Because the peripheral edge of the conductor layer overlaps with the solder resist layer and hence the peeling of the conductor can be prevented by holding the conductor with the solder resist layer as shown Fig. 41. Moreover, in the heat cycle, cracks generated starting from the boundary portion between the conductor layer and the interlaminar insulating resin layer due to the difference of thermal expansion coefficient can be controlled. As can be seen, the alignment mark is electrically isolated from the conductor layer.

IN THE CLAIMS

Please amend claims 1, 2, 7, 13 and 14 as follows (a marked-up copy of changes to the claims is attached in an Appendix to the present amendment):

D<sup>2</sup> 1. (Twice Amended) A multilayer printed circuit board comprising a plurality of interlaminar insulating layers and conductor circuits, said printed circuit board being formed by laminating a first interlaminar insulating layer on a conductor circuit of a substrate and repeating formation of conductor circuit and an interlaminar insulating layer on the first interlaminar insulating